



VMDSEMI

VUSG002R900PA

Datasheet



VMDSEMI

General Description

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
-20V	90mΩ@-4.5V	-1.4A
	120mΩ@-2.5V	
	195mΩ@-1.8V	

Symbol

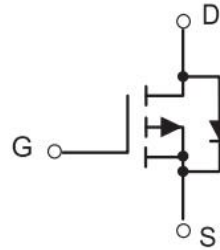


Figure 1 Symbol of VUSG002R900PA

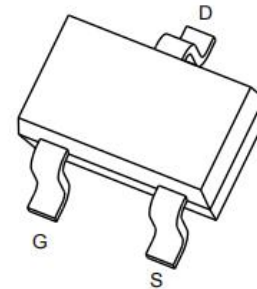
Features

- Leading Trench Technology for Low $R_{DS(on)}$
- Extending Battery Life

Package Type

Application

- High Side Load Switch
- Charging Circuit
- Single Cell Battery Applications



SOT-323

Figure 2 Package Type of VUSG002R900PA

Ordering Information

Product Name	Package
VUSG002R900PA	SOT-323

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V_{GSS}	± 10	V
Continuous Drain Current ^{Note1,2}	I_D	-1.4	A
Pulsed Drain Current	I_{DM}	-5.6	A
Total Power Dissipation ^{Note1}	P_D	0.57	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note1,2}	$R_{\theta JA}$		220		°C/W



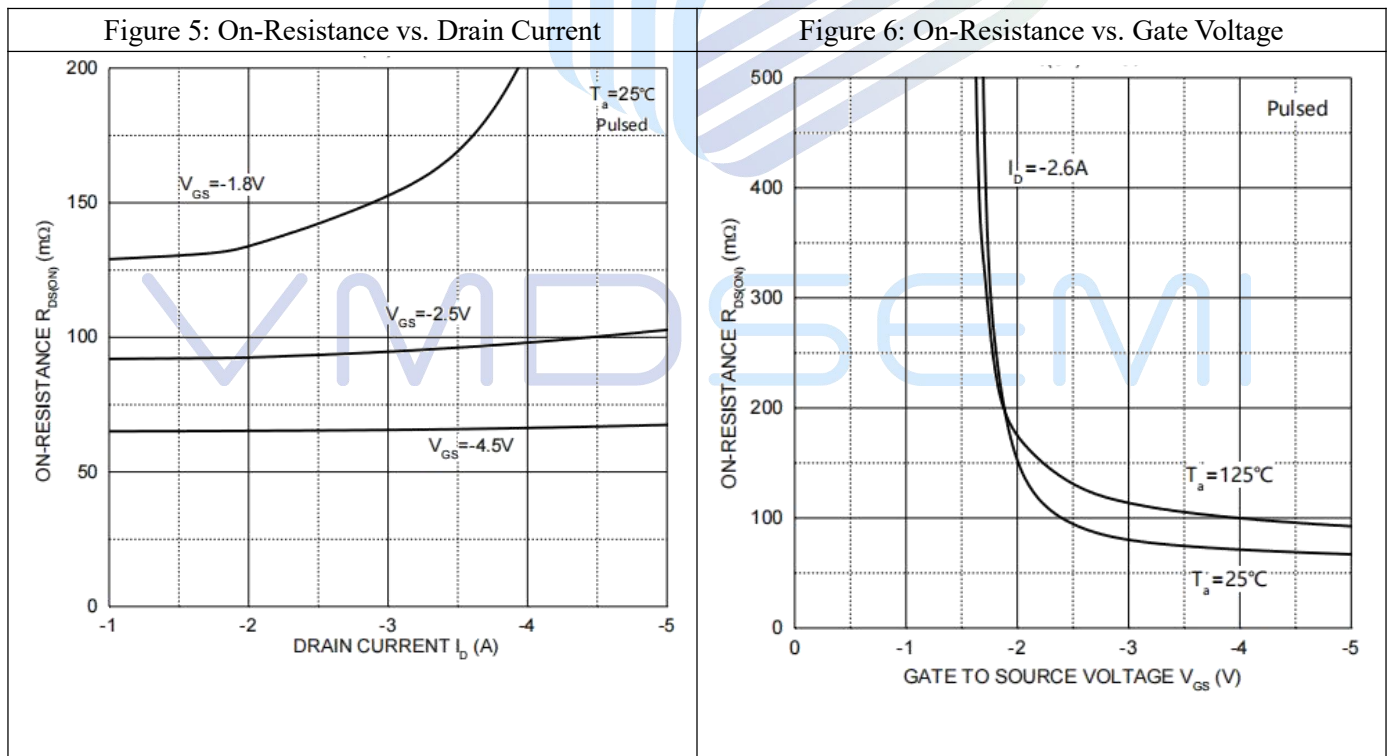
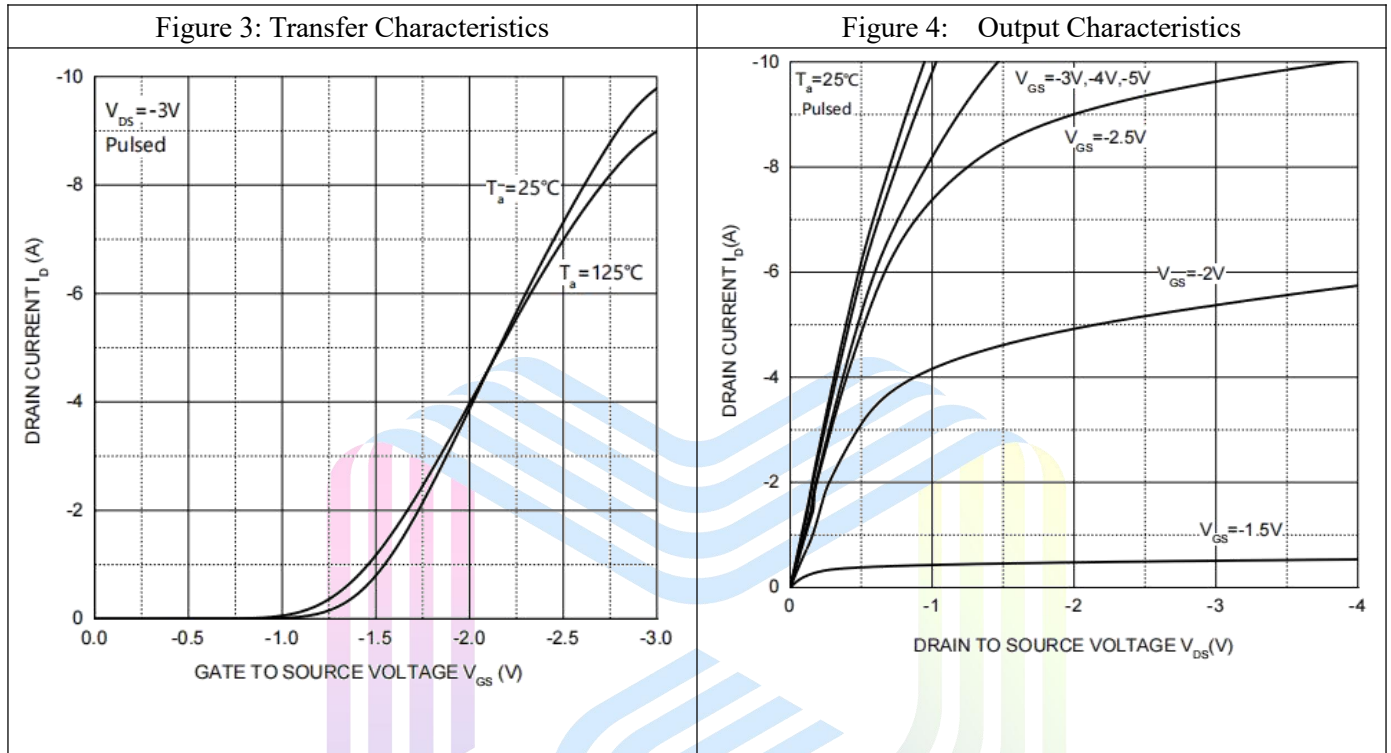
Electrical Characteristics ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

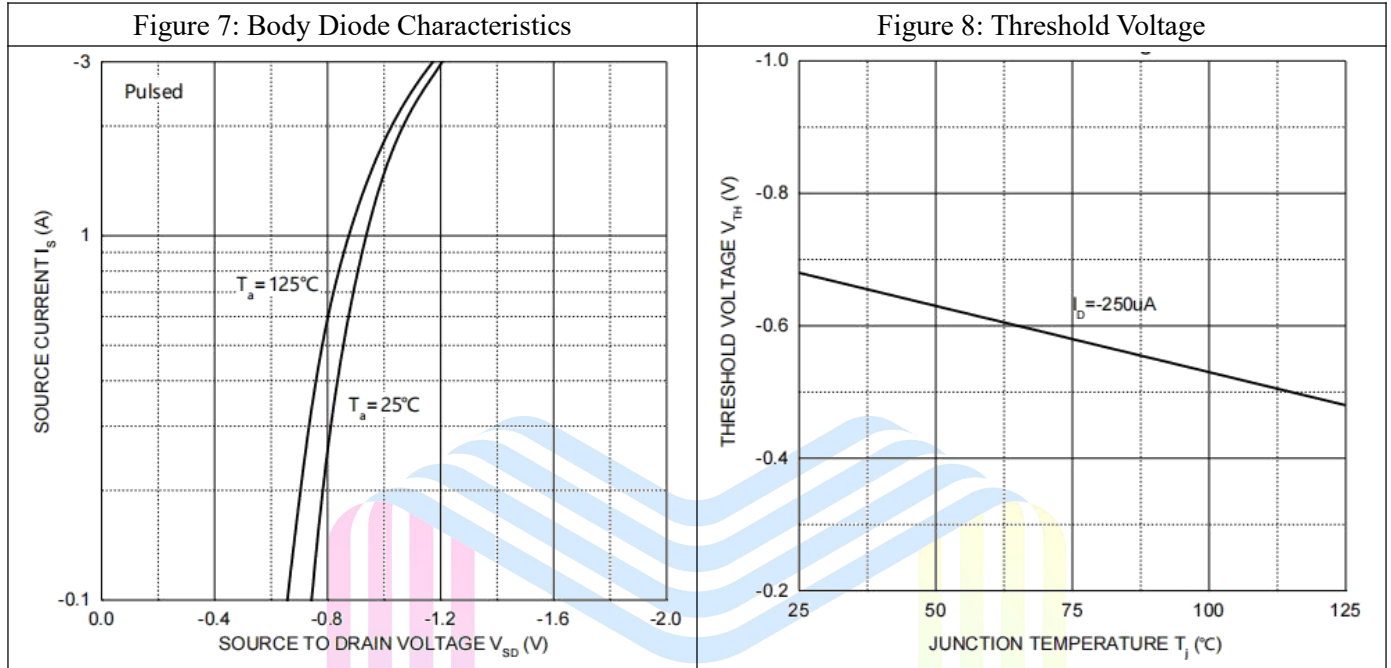
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D = -250\mu A$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -16V, V_{GS}=0V$			-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 8V, V_{DS} = 0V$			± 100	nA
Gate Threshold Voltage ^{Note3}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.7	-1.0	V
Static Drain-Source On-Resistance ^{Note3}	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -1.0A$		68	90	mΩ
		$V_{GS} = -2.5V, I_D = -0.5A$		92	120	
		$V_{GS} = -1.8V, I_D = -0.3A$		130	195	
Forward tranconductance ^{Note3}	g_{FS}	$V_{DS} = -5V, I_D = -0.8A$	8			S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS} = -10V$		350		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		75		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		67		pF
Switching Parameters						
Total Gate Charge	Q_g	$V_{DS} = -10V$		8.2		nC
Gate-source Charge	Q_{gs}	$V_{GS} = -4.5V$		1.1		
Gate-drain Charge	Q_{gd}	$I_D = -1.4A$		2.0		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = -10V$		7.0		ns
Turn-on Rise Time	t_r	$V_{GS} = -4.5V$		32		
Turn-off Delay Time	$t_{d(off)}$	$I_D = -1.4A$		49		
Turn-off Fall Time	t_f	$R_G = 3\Omega$		55		
Diode Characteristics						
Diode Forward Voltage ^{Note3}	V_{SD}	$V_{GS}=0V, I_S = -0.3A$			-1.2	V

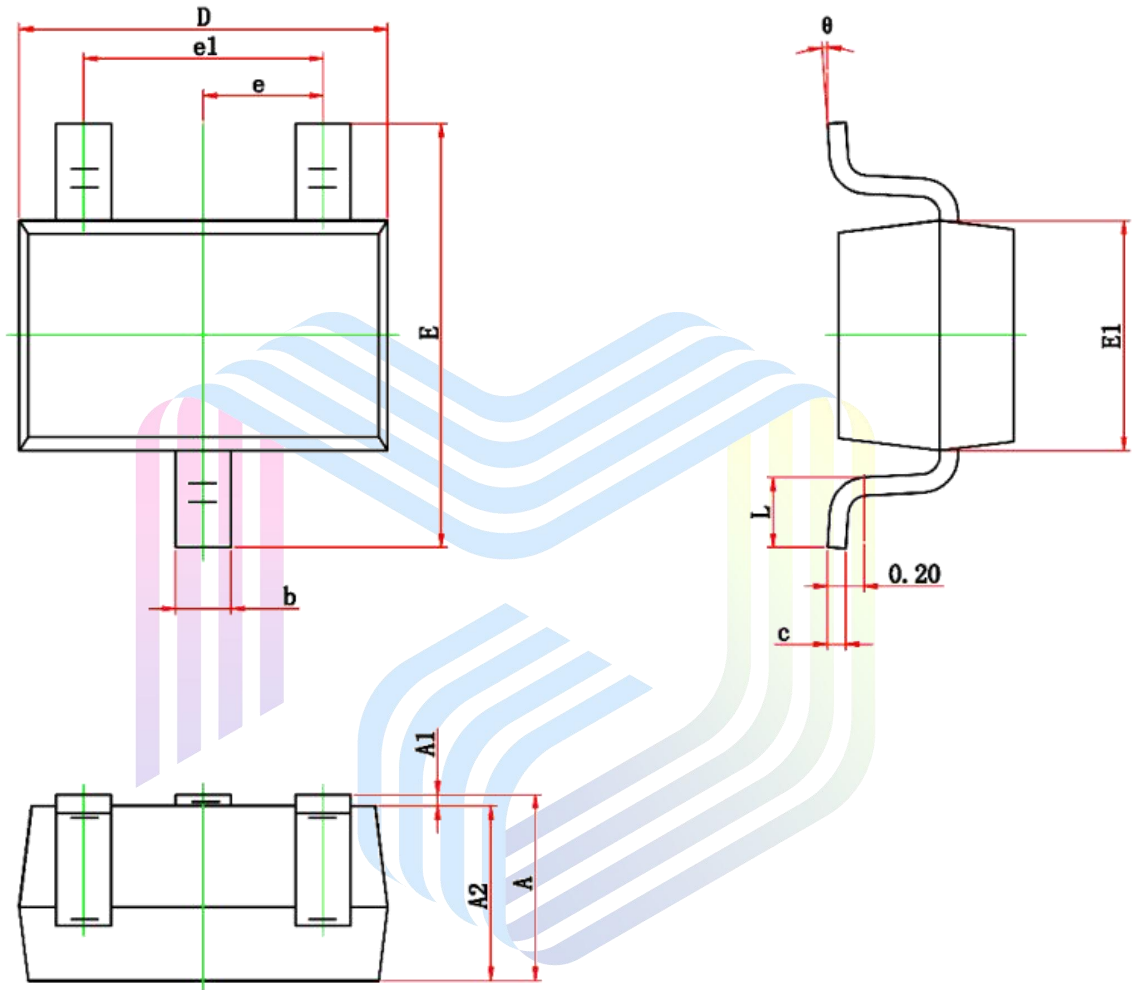
Notes :

- $R_{\theta JA}$ is measured with the device mounted on 1 in² FR4 board with 1oz. single side copper, in a still air environment with $T_A = 25^\circ\text{C}$.
- $R_{\theta JA}$ is measured in the steady state
- Pulse test : Pulse width $\leq 380\mu s$, duty cycle $\leq 2\%$.

Typical Performance Characteristics






Mechanical Dimensions:
SOT-323 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.050	0.150	0.002	0.006
D	1.900	2.200	0.075	0.087
E	2.000	2.450	0.079	0.096
E1	1.150	1.350	0.045	0.053
e	0.650TYP.		0.026TYP.	
e1	1.200	1.400	0.047	0.055
L	0.200	0.460	0.008	0.018
θ	0°	8°	0°	8°

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